

LINEAR TECHNOLOGY MATERIALS DECLARATION

1tc2050hvis5#trpbf

(Engineering Calculation)

TSOT-23

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TOTAL MASS (g) : 0.012443

| COMPONENT MATERIAL | VENDOR/ INDUSTRY NAMES | CONSTITUENT NAME | CAS NUMBER | CONSTITUENT MASS (g) | CONSTITUENT (PPM) OF MATERIAL | CONSTITUENT (PPM) OF TOTAL PKG. | | |
|--------------------------------|----------------------------------|--------------------------------|------------|----------------------|-------------------------------|---------------------------------|----------------|----------------------|
| Active Device | Linear Technology | Silicon (Si) | 7440-21-3 | 0.000567 | 1000000 | 45566.9257812 | | |
| Die Coat | Dow Corning | Silicone | 69430-27-9 | 0.000000 | 0 | 0 | | |
| Lead Frame | Cu | Copper (Cu) | 7440-50-8 | 0.004485 | 975000 | 360436.8125 | | |
| | | Iron (Fe) | 7439-89-6 | 0.000110 | 24000 | 8840.14453125 | | |
| | | Phosphorus (P) | 7723-14-0 | 0.000001 | 300 | 80.3649520874 | | |
| | | Zinc (Zn) | 7440-66-6 | 0.000003 | 700 | 241.094863892 | | |
| | | Nickel (Ni) | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Silicon (Si) | 7440-21-3 | 0.000000 | 0 | 0 | | |
| | | Magnesium (Mg) | 7439-95-4 | 0.000000 | 0 | 0 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| Lead Frame Total: | | | | 0.004599 | 1000000 | 369598.40625 | | |
| Plating | PMI | Exter. Plating Pb | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Exter. Plating Sn | 7440-31-5 | 0.000635 | 1000000 | 51050.6835938 | | |
| | | External Plating Total: | | | | 0.000635 | 1000000 | 51050.6835938 |
| | | Inter. Plating Ni | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Inter. Plating Ag | 7440-22-4 | 0.000080 | 1000000 | 6429.19580078 | | |
| Internal Plating Total: | | | | 0.000080 | 1000000 | 6429.19580078 | | |
| Die Attach | ELECTRICALLY CONDUCTIVE ADHESIVE | Silver (Ag) | 7440-22-4 | 0.000409 | 750000 | 32869.265625 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| | | Lead (Pb) | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.000000 | 0 | 0 | | |
| | | Indium (In) | 7440-74-6 | 0.000000 | 0 | 0 | | |
| | | Metal Oxide | | 0.000000 | 0 | 0 | | |
| | | Antimony (Sb) | 7440-36-0 | 0.000000 | 0 | 0 | | |
| | | Resin (EP) | | 0.000136 | 250000 | 10929.6337891 | | |
| Die Attach Total: | | | | 0.000545 | 1000000 | 43798.9023438 | | |
| Encapsulation | MULTI-AROMATIC RESIN Br/Sb FREE | Resin (EP) | | 0.000775 | 130000 | 62282.8398438 | | |
| | | Bromine (Br) | 40039-93-8 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.004947 | 830000 | 397565.4375 | | |
| | | Antimony Trioxide (Sb2O3) | 1309-64-4 | 0.000000 | 0 | 0 | | |
| | | Metal Hydroxide | | 0.000209 | 35000 | 16796.2753906 | | |
| | | Carbon Black (C) | 1333-86-4 | 0.000030 | 5000 | 2410.94848633 | | |
| | | Encapsulation Total: | | | | 0.005961 | 1000000 | 479055.5 |
| Bond Wire Estimated | AFW/TANAKA/ Kn | Gold (Au) | 7440-57-5 | 0.000056 | 1000000 | 4500.4375 | | |
| | | | | | TOTAL MASS (g) : | 0.012443 | | |